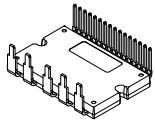
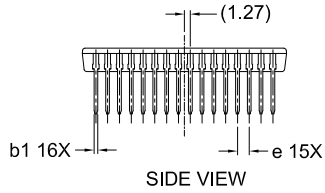


# MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS



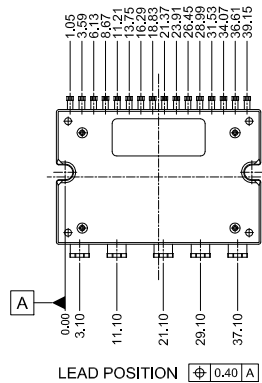
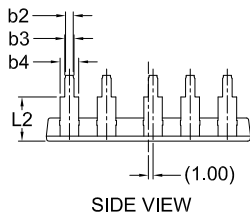
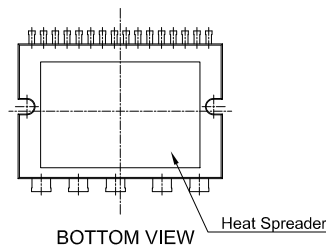
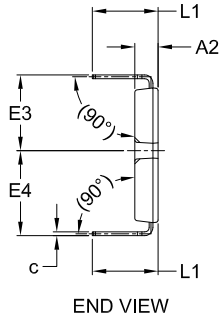
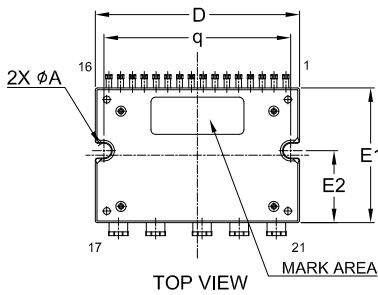
## APM21 AUTOMOTIVE MODULE CASE MODBQ ISSUE 0

DATE 24 NOV 2022



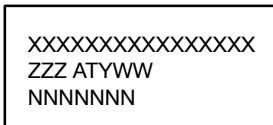
### NOTES:

1. DIMENSIONING AND TOLERANCING PER. ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR EXTRUSIONS.



DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A2	4.90	5.00	5.10
b1	0.70	0.80	0.90
b2	1.50	1.70	1.90
b3	1.90	2.00	2.10
b4	3.90	4.00	4.10
c	0.75	0.80	0.90
D	43.90	44.00	44.10
E1	28.90	29.00	29.10
E2	15.40	15.50	15.60
E3	15.90	16.30	16.70
E4	17.90	18.30	18.70
e	2.54 BASIC		
L1	13.85	14.15	14.45
L2	9.20	9.50	9.80
q	40.10	40.20	40.30
φA	3.10	3.20	3.30

### GENERIC MARKING DIAGRAM\*



XXXX = Specific Device Code  
 ZZZ = Lot ID  
 AT = Assembly & Test Location  
 Y = Year  
 WW = Work Week  
 NNN = Serial Number

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "μ", may or may not be present. Some products may not follow the Generic Marking.

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<b>DESCRIPTION:</b>	<b>APM21 AUTOMOTIVE MODULE</b>	<b>PAGE 1 OF 1</b>

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